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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/798,970	03/11/2004	Yasushi Haga	9319S-000728	5341
27572	7590 06/15/2005		EXAM	INER
HARNESS, DICKEY & PIERCE, P.L.C.			HO, TU TU V	
P.O. BOX 828 BLOOMFIELD HILLS, MI 48303			ART UNIT	PAPER NUMBER
		2818		
	, and the second			

DATE MAILED: 06/15/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)
	10/798,970	HAGA ET AL.
Office Action Summary	Examiner	Art Unit
	Tu-Tu Ho	2818
The MAILING DATE of this communication a Period for Reply	appears on the cover sheet w	ith the correspondence address
A SHORTENED STATUTORY PERIOD FOR REST THE MAILING DATE OF THIS COMMUNICATION - Extensions of time may be available under the provisions of 37 CFR after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a construction of the period for reply is specified above, the maximum statutory perion of the period for reply within the set or extended period for reply will, by state and the period for reply will, by state and patent term adjustment. See 37 CFR 1.704(b).	N. 1.136(a). In no event, however, may a reply within the statutory minimum of thi iod will apply and will expire SIX (6) MO tute, cause the application to become A	reply be timely filed rty (30) days will be considered timely. NTHS from the mailing date of this communication. BANDONED (35 U.S.C. § 133).
Status .		
 1) ⊠ Responsive to communication(s) filed on 19 2a) ☐ This action is FINAL. 2b) ⊠ T 3) ☐ Since this application is in condition for allow closed in accordance with the practice under 	his action is non-final. wance except for formal mat	
Disposition of Claims		
4) Claim(s) 1-10 is/are pending in the application 4a) Of the above claim(s) 10 is/are withdraw 5) Claim(s) is/are allowed. 6) Claim(s) 1-9 is/are rejected. 7) Claim(s) is/are objected to. 8) Claim(s) are subject to restriction and Application Papers	n from consideration.	
9)☐ The specification is objected to by the Exam	iner.	
10)⊠ The drawing(s) filed on <u>28 July 2004</u> is/are:		
Applicant may not request that any objection to t Replacement drawing sheet(s) including the con	- · ·	
11) The oath or declaration is objected to by the	·	
Priority under 35 U.S.C. § 119		
12) Acknowledgment is made of a claim for fore a) All b) Some * c) None of: 1. Certified copies of the priority docume 2. Certified copies of the priority docume 3. Copies of the certified copies of the papplication from the International Bur * See the attached detailed Office action for a	ents have been received. ents have been received in a priority documents have been reau (PCT Rule 17.2(a)).	Application No n received in this National Stage
Attachment(s) 1) Motice of References Cited (PTO-892)	4) ☐ Interview	Summary (PTO-413)
 2) Notice of Traffsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/Paper No(s)/Mail Date 	Paper No	(s)/Mail Date Informal Patent Application (PTO-152)

DETAILED ACTION

Oath/Declaration

1. The oath/declaration filed on 07/28/2004 is acceptable.

Election/ Restriction

- 2. Applicant's election of Invention II, claims 1-9, in the reply filed on 05/19/2005 is acknowledged. Because applicant did not distinctly and specifically point out the supposed errors in the restriction requirement, the election has been treated as an election without traverse (MPEP § 818.03(a)). Specifically, Applicant did not prove that the two inventions were not distinct.
- 3. Claim 10 is withdrawn from further consideration pursuant to 37 CFR 1.142(b), as being drawn to a nonelected invention, there being no allowable generic or linking claim. Applicant timely traversed the restriction (election) requirement in the reply filed on 05/19/2005, as noted above.

Drawings

4. Figures 13A through 13C should be designated by a legend such as --Prior Art-- because only that which is old is illustrated. See MPEP § 608.02(g). Corrected drawings in compliance with 37 CFR 1.121(d) are required in reply to the Office action to avoid abandonment of the

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application. The replacement sheet(s) should be labeled "Replacement Sheet" in the page header (as per 37 CFR 1.121(d)) so as not to obstruct any portion of the drawing figures. If the changes are not accepted by the examiner, the applicant will be notified and informed of any required corrective action in the next Office action. The objection to the drawings will not be held in abeyance.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. §103(a) which forms the basis for all obviousness rejections set forth in this Office action:

- (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 5. Claims 2 and 8 are rejected under 35 U.S.C. §103(a) as being unpatentable over Nistler et al. U.S. Patent 6,096,616 (the '616 reference).

The '616 reference discloses in Fig. 10 and respective portions of the specification a semiconductor device and a method of manufacturing thereof substantially as claimed.

Referring to claims 2 and 8, the reference discloses a semiconductor device and a method of manufacturing thereof comprising:

- a semiconductor region in which an impurity of one conductivity type is doped;
- a gate insulation layer (no number) formed on the semiconductor region;
- a gate electrode (no number) formed on the gate insulation layer;
- a lightly doped layer (120, or 124, or 128), formed in a region from a principal surface of the semiconductor region to a first depth of the semiconductor region, in which a first impurity

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of another conductivity type (although the reference does not explicitly disclose that the first impurity is of another conductivity type, the first impurity is of the another conductivity type for the device to function) is implanted into the semiconductor region with a first dose amount; and

a heavily doped layer, formed in a depth direction from the principal surface of the semiconductor region, in which a second impurity of the another conductivity type is implanted into the semiconductor region with a second dose amount so that a peak position of a concentration of the second impurity exists at a second depth position, the second depth position being less than the first depth (column 3, lines 12-20, column 4, lines 18-23, column 6, first paragraph, and column 8, claim 7).

However, the reference does not disclose any specific numerical doping depth for the different doping depths. Specifically, although the reference teaches that the second depth position is less than the first depth, the reference fails to disclose that the second depth position is less than the first depth by about 0.15 µm or more.

Nevertheless, because the '616 reference does not disclose any specific numerical depth, one of ordinary skill in the art at the time the invention was made would be able to select various numerical doping depths, so long as the second depth position is less than the first depth, therefore such selecting would not be patentable.

6. Claims 1 and 7 are rejected under 35 U.S.C. §103(a) as being unpatentable over Nistler et al. U.S. Patent 6,096,616 (the '616 reference) or as being unpatentable over Nistler in view of Huster et al. U.S. Patent 6,395,606 (the '606 reference).

The '616 reference discloses in Fig. 10 and respective portions of the specification a semiconductor device and a method of manufacturing thereof substantially as claimed.

Referring to claims 1 and 7, the reference discloses a semiconductor device and a method of manufacturing thereof comprising:

- a semiconductor region in which an impurity of one conductivity type is doped;
- a gate insulation layer (no number) formed on the semiconductor region;
- a gate electrode (no number) formed on the gate insulation layer;
- a lightly doped layer (120, or 124, or 128), formed in a region from a principal surface of the semiconductor region to a first depth of the semiconductor region, in which a first impurity of another conductivity type (although the reference does not explicitly disclose that the first impurity is of another conductivity type, the first impurity is of the another conductivity type for the device to function) is implanted into the semiconductor region with a first dose amount; and

a heavily doped layer, formed in a region from the principal surface of the semiconductor region to a second depth, in which a second impurity of the another conductivity type is implanted into the semiconductor region with a second dose amount; the second dose amount being large than the first dose amount (column 3, lines 12-20, column 4, lines 18-23, column 6, first paragraph, and column 8, claim 7).

wherein the second depth is less than the first depth (column 3, lines 12-20, column 4, lines 18-23, column 6, first paragraph, and column 8, claim 7).

However, the reference fails to disclose that the second dose amount is in a range of the first dose amount or more to 1×10^{15} /cm² or less. In other words, although the '616 reference

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discloses that the second dose amount is large than the first dose amount as claimed, the reference fails to established an upper limit for the dose amount of 1×10^{15} /cm² or less.

Nevertheless, since the '616 reference is completely silent as to the specific numerical dosage, one of ordinary skill in the art at the time the invention was made would be able to select various numerical dose amounts, so long as the second dose amount is large than the first dose amount, therefore such selecting would not be patentable.

Alternatively, Huster, in also disclosing a semiconductor device and a method of manufacturing thereof, teaches that a second dose amount (for the heavily doped layer 113) is about 1×10^{15} /cm² (column 4, lines 40-50, " 1×10^{15} atoms cm⁻²"), thereby teaching a dose amount of about 1×10^{15} /cm² for the second dose amount.

Therefore, it would have been obvious to one of ordinary skill in the art the time the invention was made to form the '616 reference's second dose amount such that it has a numerical dosage of about 1×10^{15} /cm². One would have been motivated to make such a change because the '616 reference fails to establish a numerical dose amount for the second dose amount and because such dose amount for the second dose amount has been taught in the art.

7. Claims 3-6 and 9 are rejected under 35 U.S.C. §103(a) as being unpatentable over Nistler et al. U.S. Patent 6,096,616 (the '616 reference) or as being unpatentable over Nistler in view of Huster et al. U.S. Patent 6,395,606 (the '606 reference).

Claims 1 and 2 comprise all limitations of 3 and claims 7 and 8 comprise all limitations of 9, therefore claims 3 and 9 are rejected similarly as detailed above for claims 1 and 7 and claims 2 and 8.

Referring to claim 4, although the '616 reference does not explicitly disclose N-type and P-type as the one conductivity type and as the another conductivity type, N-type (negative type) and P-type (positive type) as the one conductivity type and as the another conductivity type.

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Referring to claim 5, although the reference fails to teach that the second impurity type is arsenic, selecting arsenic as the second impurity type was known in the art, for example the selecting arsenic as the second impurity type as disclosed by the '606 reference, therefore such selecting would have been obvious.

Referring to claim 6, the '616 reference further discloses a trench structure (no number) that isolates the semiconductor region.

Conclusion

8. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Tu-Tu Ho whose telephone number is (571) 272-1778. The examiner can normally be reached on 6:30 am - 5:00 pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, DAVID NELMS can be reached on (571) 272-1787. The fax phone number for the organization where this application or proceeding is assigned is (703) 872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR

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system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Tu-Tu Ho

June 06, 2005